

Electronic Patent Application Fee Transmittal

Application Number:	10598515			
Filing Date:	01-Sep-2006			
Title of Invention:	SEALANT EPOXY-RESIN MOLDING MATERIAL, AND ELECTRONIC COMPONENT DEVICE			
First Named Inventor/Applicant Name:	Seiichi Akagi			
Filer:	Joerg-Uwe V. Szipl/Janice Rosier			
Attorney Docket Number:	MIYOSH0008			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
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Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				180